

Notification Number:	20260930001.0	Notification Issued	September 30, 2026
Datasheet for SN74LVC1G00, SN74LVC1G02, SN74LVC1G240, SN74LVC1G80, SN74LVC1G32, SN74LVC1G126, SN74LVC1G08, SN74LVC1G132, SN74LVC1G38, SN74LVC1G79, SN74LVC1G125, and SN74LVC1G86			

Change Type(s)	Data Sheet/Electrical Specification
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Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



SN74LVC1G00

SCES212AC – APRIL 1999 – REVISED AUGUST 2026

Changes from April 1, 2014 to August 12, 2026 (from Revision AB (April 2014) to Revision AC (August 2026))

	Page
• Updated <i>Device Information</i> table to include body and package dimensions.....	1
• Changed <i>Handling Ratings</i> to <i>ESD Ratings</i>	4
• Moved <i>Storage temperature range</i> from <i>Handling Ratings</i> to <i>Absolute Maximum Ratings</i>	4
• Updated format for <i>Thermal Information</i> table.....	5
• Changed Junction-to-ambient thermal resistance value for DBV package from: 229°C/W to: 357.1°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for DBV package from: 164°C/W to: 263.7°C/W.....	5
• Changed Junction-to-board characterization value for DBV package from: 62°C/W to: 264.4°C/W.....	5
• Changed Junction-to-top characterization value for DBV package from: 44°C/W to: 195.6°C/W.....	5
• Changed Junction-to-board characterization value for DBV package from: 62°C/W to: 262.2°C/W.....	5
• Changed Junction-to-ambient thermal resistance value for DCK package from: 278°C/W to: 371°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for DCK package from: 93°C/W to: 297.5°C/W.....	5
• Changed Junction-to-board characterization value for DCK package from: 65°C/W to: 258.6°C/W.....	5
• Changed Junction-to-top characterization value for DCK package from: 2°C/W to: 195.6°C/W.....	5
• Changed Junction-to-board characterization value for DCK package from: 64°C/W to: 256.2°C/W.....	5
• Removed redundant t_{pd} specification from <i>Switching Characteristics</i> , –40°C to 125°C	7
• Added parallel trace spacing recommendation to layout guidelines. Changed wording of "Avoid branches; buffer signals that must branch separately" to "Avoid branches; buffer each signal that must branch separately"	14
• Updated <i>Overview</i> , <i>Application and Implementation</i> , <i>Device and Documentation Support</i> sections to extend detailed feature descriptions and more detailed information.	16



SN74LVC1G02

SCES213Y – APRIL 1999 – REVISED AUGUST 2026

Changes from April 1, 2014 to August 12, 2026 (from Revision X (April 2014) to Revision Y (August 2026))

	Page
• Updated <i>Device Information</i> table to include body and package dimensions.....	1
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Moved T_{stg} to <i>Absolute Maximum Ratings</i> table.....	4
• Changed <i>Handling Ratings</i> to <i>ESD Ratings</i>	4
• Updated format for <i>Thermal Information</i> table.....	5
• Changed Junction-to-ambient thermal resistance value for DBV package from: 229°C/W to: 357.1°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for DBV package from: 164°C/W to: 263.7°C/W.....	5
• Changed Junction-to-board characterization value for DBV package from: 62°C/W to: 264.4°C/W.....	5
• Changed Junction-to-top characterization value for DBV package from: 44°C/W to: 195.6°C/W.....	5

• Changed Junction-to-board characterization value for DBV package from: 62°C/W to: 262.2°C/W.....	5
• Changed Junction-to-ambient thermal resistance value for DCK package from: 278°C/W to: 371°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for DCK package from: 93°C/W to: 297.5°C/W.....	5
• Changed Junction-to-board characterization value for DCK package from: 65°C/W to: 258.6°C/W.....	5
• Changed Junction-to-top characterization value for DCK package from: 2°C/W to: 195.6°C/W.....	5
• Changed Junction-to-board characterization value for DCK package from: 64°C/W to: 256.2°C/W.....	5
• Changed Junction-to-ambient thermal resistance value for DRL package from: 243°C/W to: 364.1°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for DRL package from: 78°C/W to: 280.6°C/W.....	5
• Changed Junction-to-board characterization value for DRL package from: 78°C/W to: 261.5°C/W.....	5
• Changed Junction-to-top characterization value for DRL package from: 10°C/W to: 195.6°C/W.....	5
• Changed tpd maximum value at $V_{CC} = 1.8V \pm 0.15V$ from: 7.2ns to: 7.7ns.....	6
• Changed tpd maximum value at $V_{CC} = 2.5V \pm 0.2V$ from: 4.4ns to: 4.5ns.....	6
• Changed tpd maximum value at $V_{CC} = 1.8V \pm 0.15V$ from: 8ns to: 8.4ns.....	6
• Added parallel trace spacing recommendation to layout guidelines. Changed wording of "Avoid branches; buffer signals that must branch separately" to "Avoid branches; buffer each signal that must branch separately".....	14
• Updated <i>Overview, Application and Implementation, Device and Documentation Support</i> sections to extend detailed feature descriptions and more detailed information.	16



SN74LVC1G240

SCES305M – JANUARY 2001 – REVISED AUGUST 2026

Changes from December 1, 2013 to August 12, 2026 (from Revision L (December 2013) to Revision M (August 2026))

	Page
• Updated <i>Device Information</i> table to include body and package dimensions.....	1
• Added <i>Applications, Device Information</i> table, <i>Pin Configuration and Functions</i> section, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Feature Description</i> section, <i>Device Functional Modes, Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section.....	1
• Added <i>Device Information</i> table.....	1
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Moved T_{stg} to <i>Absolute Maximum Ratings</i> table.....	4
• Added <i>Thermal Information</i> table.....	5
• Changed Junction-to-ambient thermal resistance value for DBV package from: 206°C/W to: 357.1°C/W.....	5
• Changed Junction-to-ambient thermal resistance value for DCK package from: 252°C/W to: 371°C/W.....	5
• Updated <i>Overview, Application and Implementation, Device and Documentation Support</i> sections to extend detailed feature descriptions and more detailed information.	9
• Added parallel trace spacing recommendation to layout guidelines. Changed wording of "Avoid branches; buffer signals that must branch separately" to "Avoid branches; buffer each signal that must branch separately".....	14



SN74LVC1G80

SCES221T – APRIL 1999 – REVISED AUGUST 2026

Changes from November 1, 2016 to August 12, 2026 (from Revision S (November 2016) to Revision T (August 2026))

	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Added <i>Thermal Information</i> table.....	5
• Changed Junction-to-ambient thermal resistance value for DBV package from: 243.4°C/W to: 357.1°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for DBV package from: 179°C/W to: 263.7°C/W.....	5
• Changed Junction-to-board characterization value for DBV package from: 77.6°C/W to: 264.4°C/W.....	5
• Changed Junction-to-top characterization value for DBV package from: 58.4°C/W to: 195.6°C/W.....	5
• Changed Junction-to-board characterization value for DBV package from: 77°C/W to: 262.2°C/W.....	5
• Changed Junction-to-ambient thermal resistance value for DCK package from: 278.9°C/W to: 371°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for DCK package from: 121.3°C/W to: 297.5°C/W.....	5
• Changed Junction-to-board characterization value for DCK package from: 65.6°C/W to: 258.6°C/W.....	5
• Changed Junction-to-top characterization value for DCK package from: 7.5°C/W to: 195.6°C/W.....	5
• Changed Junction-to-board characterization value for DCK package from: 64.9°C/W to: 256.2°C/W.....	5

Changes from August 1, 2015 to August 12, 2026 (from Revision V (August 2015) to Revision W (August 2026))
Page

• Updated <i>Device Information</i> table to include body and package dimensions.....	1
• Added <i>Applications, Device Information table, Pin Configuration and Functions</i> section, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section.....	1
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Added <i>Thermal Information</i> table.....	6
• Changed Junction-to-ambient thermal resistance value for DBV package from: 229°C/W to: 357.1°C/W.....	6
• Changed Junction-to-case (top) thermal resistance value for DBV package from: 164°C/W to: 263.7°C/W.....	6
• Changed Junction-to-board characterization value for DBV package from: 62°C/W to: 264.4°C/W.....	6
• Changed Junction-to-top characterization value for DBV package from: 44°C/W to: 195.6°C/W.....	6
• Changed Junction-to-board characterization value for DBV package from: 62°C/W to: 262.2°C/W.....	6
• Changed Junction-to-ambient thermal resistance value for DCK package from: 278°C/W to: 371°C/W.....	6
• Changed Junction-to-case (top) thermal resistance value for DCK package from: 93°C/W to: 297.5°C/W.....	6
• Changed Junction-to-board characterization value for DCK package from: 65°C/W to: 258.6°C/W.....	6
• Changed Junction-to-top characterization value for DCK package from: 2°C/W to: 195.6°C/W.....	6
• Changed Junction-to-board characterization value for DCK package from: 64°C/W to: 256.2°C/W.....	6
• Changed Junction-to-ambient thermal resistance value for DRL package from: 243°C/W to: 364.1°C/W.....	6
• Changed Junction-to-case (top) thermal resistance value for DRL package from: 78°C/W to: 280.6°C/W.....	6
• Changed Junction-to-board characterization value for DRL package from: 78°C/W to: 261.5°C/W.....	6
• Changed Junction-to-top characterization value for DRL package from: 10°C/W to: 195.6°C/W.....	6
• Changed Junction-to-board characterization value for DRL package from: 77°C/W to: 259.2°C/W.....	6
• Added parallel trace spacing recommendation to layout guidelines. Changed wording of "Avoid branches; buffer signals that must branch separately" to "Avoid branches; buffer each signal that must branch separately".....	15
• Updated <i>Overview, Application and Implementation, Device and Documentation Support</i> sections to extend detailed feature descriptions and more detailed information.	17

Changes from February 1, 2014 to June 1, 2026 (from Revision R (February 2014) to Revision S (August 2026))
Page

• Updated <i>Device Information</i> table to include body and package dimensions.....	1
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Updated format for <i>Thermal Information</i> table.....	5
• Extended <i>Thermal Information</i> table to include $R_{\theta JC(top)}$, $R_{\theta JB}$, Ψ_{JT} , Ψ_{JB} , $R_{\theta JC(bot)}$	5
• Changed Junction-to-ambient thermal resistance value for DBV package from: 206°C/W to: 357.1°C/W.....	5
• Changed Junction-to-ambient thermal resistance value for DCK package from: 252°C/W to: 371°C/W.....	5
• Changed Junction-to-ambient thermal resistance value for DRL package from: 142°C/W to: 364.1°C/W.....	5
• Updated <i>Overview, Application and Implementation, Device and Documentation Support</i> sections to extend detailed feature descriptions and more detailed information.	9
• Added parallel trace spacing recommendation to layout guidelines. Changed wording of "Avoid branches; buffer signals that must branch separately" to "Avoid branches; buffer each signal that must branch separately"	15

Changes from May 1, 2019 to August 12, 2026 (from Revision Z (May 2019) to Revision AA (August 2026))

	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Updated <i>Device Information</i> table to include body and package dimensions.....	1
• Updated format for <i>Thermal Information</i> table.....	5
• Changed Junction-to-ambient thermal resistance value for DBV package from: 207.6°C/W to: 357.1°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for DBV package from: 145.2°C/W to: 263.7°C/W.....	5
• Changed Junction-to-board characterization value for DBV package from: 53.5°C/W to: 264.4°C/W.....	5
• Changed Junction-to-top characterization value for DBV package from: 37.5°C/W to: 195.6°C/W.....	5
• Changed Junction-to-board characterization value for DBV package from: 53.1°C/W to: 262.2°C/W.....	5
• Changed Junction-to-ambient thermal resistance value for DCK package from: 283.1°C/W to: 371°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for DCK package from: 92.3°C/W to: 297.5°C/W.....	5
• Changed Junction-to-board characterization value for DCK package from: 60.9°C/W to: 258.6°C/W.....	5
• Changed Junction-to-top characterization value for DCK package from: 1.7°C/W to: 195.6°C/W.....	5
• Changed Junction-to-board characterization value for DCK package from: 60.1°C/W to: 256.2°C/W.....	5
• Changed Junction-to-ambient thermal resistance value for DRL package from: 242.9°C/W to: 364.1°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for DRL package from: 77.5°C/W to: 280.6°C/W.....	5
• Changed Junction-to-board characterization value for DRL package from: 77.5°C/W to: 261.5°C/W.....	5
• Changed Junction-to-top characterization value for DRL package from: 9.6°C/W to: 195.6°C/W.....	5
• Changed Junction-to-board characterization value for DRL package from: 77.3°C/W to: 259.2°C/W.....	5
• Updated <i>Overview, Application and Implementation, Device and Documentation Support</i> sections to extend detailed feature descriptions and more detailed information.	9
• Added parallel trace spacing recommendation to layout guidelines. Changed wording of "Avoid branches; buffer signals that must branch separately" to "Avoid branches; buffer each signal that must branch separately"	14



SN74LVC1G132

SCES546E – FEBRUARY 2004 – REVISED AUGUST 2026

Changes from April 1, 2014 to August 12, 2026 (from Revision D (June 2017) to Revision E (August 2026))

	Page
• Updated <i>Device Information</i> table to include body and package dimensions.....	1
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Updated format for <i>Thermal Information</i> table.....	5
• Extended <i>Thermal Information</i> table to include $R_{\theta JC(top)}$, $R_{\theta JB}$, Ψ_{JT} , Ψ_{JB} , $R_{\theta JC(bot)}$	5
• Changed Junction-to-ambient thermal resistance value for DBV package from: 206°C/W to: 357.1°C/W.....	5
• Changed Junction-to-ambient thermal resistance value for DCK package from: 252°C/W to: 371°C/W.....	5
• Updated <i>Overview, Application and Implementation, Device and Documentation Support</i> sections to extend detailed feature descriptions and more detailed information.	9
• Added parallel trace spacing recommendation to layout guidelines. Changed wording of "Avoid branches; buffer signals that must branch separately" to "Avoid branches; buffer each signal that must branch separately"	14



SN74LVC1G38

SCES538H – JANUARY 2004 – REVISED AUGUST 2026

Changes from February 1, 2020 to August 12, 2026 (from Revision G (February 2020) to Revision H (August 2026))

Page

• Updated <i>Device Information</i> table to include body and package dimensions.....	1
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Added <i>Thermal Information</i> table.....	5
• Changed Junction-to-ambient thermal resistance value for DBV package from: 247.2°C/W to: 357.1°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for DBV package from: 154.5°C/W to: 263.7°C/W..	5
• Changed Junction-to-board characterization value for DBV package from: 86.8°C/W to: 264.4°C/W.....	5
• Changed Junction-to-top characterization value for DBV package from: 58°C/W to: 195.6°C/W.....	5
• Changed Junction-to-board characterization value for DBV package from: 86.4°C/W to: 262.2°C/W.....	5
• Changed Junction-to-ambient thermal resistance value for DCK package from: 276.1°C/W to: 371°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for DCK package from: 178.9°C/W to: 297.5°C/W..	5
• Changed Junction-to-board characterization value for DCK package from: 70.9°C/W to: 258.6°C/W.....	5
• Changed Junction-to-top characterization value for DCK package from: 47°C/W to: 195.6°C/W.....	5
• Changed Junction-to-board characterization value for DCK package from: 69.3°C/W to: 256.2°C/W.....	5



SN74LVC1G79

SCES220V – APRIL 1999 – REVISED AUGUST 2026

Changes from April 1, 2017 to August 12, 2026 (from Revision U (April 2017) to Revision V (August 2026))

Page

• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Changed Junction-to-ambient thermal resistance value for DBV package from: 247.2°C/W to: 357.1°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for DBV package from: 154.5°C/W to: 263.7°C/W..	5
• Changed Junction-to-board characterization value for DBV package from: 86.8°C/W to: 264.4°C/W.....	5
• Changed Junction-to-top characterization value for DBV package from: 58°C/W to: 195.6°C/W.....	5
• Changed Junction-to-board characterization value for DBV package from: 86.4°C/W to: 262.2°C/W.....	5
• Changed Junction-to-ambient thermal resistance value for DCK package from: 277.6°C/W to: 371°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for DCK package from: 179.5°C/W to: 297.5°C/W..	5
• Changed Junction-to-board characterization value for DCK package from: 75.9°C/W to: 258.6°C/W.....	5
• Changed Junction-to-top characterization value for DCK package from: 49.7°C/W to: 195.6°C/W.....	5
• Changed Junction-to-board characterization value for DCK package from: 75.1°C/W to: 256.2°C/W.....	5
• Changed Junction-to-ambient thermal resistance value for DRL package from: 294.3°C/W to: 364.1°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for DRL package from: 129.9°C/W to: 280.6°C/W..	5
• Changed Junction-to-board characterization value for DRL package from: 143.4°C/W to: 261.5°C/W.....	5
• Changed Junction-to-top characterization value for DRL package from: 14.3°C/W to: 195.6°C/W.....	5
• Changed Junction-to-board characterization value for DRL package from: 144°C/W to: 259.2°C/W.....	5
• Added <i>Thermal Information</i> table.....	5



SN74LVC1G125

SCES223U – APRIL 1999 – REVISED AUGUST 2026

Changes from October 1, 2014 to August 13, 2026 (from Revision T (October 2014) to Revision U (August 2026))

Page

• Updated <i>Device Information</i> table to include body and package dimensions.....	1
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Changed <i>Handling Ratings</i> to <i>ESD Ratings</i> .	4
• Moved <i>Storage temperature range</i> from <i>Handling Ratings</i> to <i>Absolute Maximum Ratings</i> .	4
• Updated format for <i>Thermal Information</i> table.....	5
• Changed Junction-to-ambient thermal resistance value for DBV package from: 229°C/W to: 357.1°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for DBV package from: 164°C/W to: 263.7°C/W.....	5
• Changed Junction-to-board characterization value for DBV package from: 62°C/W to: 264.4°C/W.....	5
• Changed Junction-to-top characterization value for DBV package from: 44°C/W to: 195.6°C/W.....	5

• Changed Junction-to-board characterization value for DBV package from: 62°C/W to: 262.2°C/W.....	5
• Changed Junction-to-ambient thermal resistance value for DCK package from: 278°C/W to: 371°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for DCK package from: 93°C/W to: 297.5°C/W.....	5
• Changed Junction-to-board characterization value for DCK package from: 65°C/W to: 258.6°C/W.....	5
• Changed Junction-to-top characterization value for DCK package from: 2°C/W to: 195.6°C/W.....	5
• Changed Junction-to-board characterization value for DCK package from: 64°C/W to: 256.2°C/W.....	5
• Changed Junction-to-ambient thermal resistance value for DRL package from: 243°C/W to: 364.1°C/W.....	5
• Changed Junction-to-case (top) thermal resistance value for DRL package from: 78°C/W to: 280.6°C/W.....	5
• Changed Junction-to-board characterization value for DRL package from: 78°C/W to: 261.5°C/W.....	5
• Changed Junction-to-top characterization value for DRL package from: 10°C/W to: 195.6°C/W.....	5
• Changed Junction-to-board characterization value for DRL package from: 77°C/W to: 259.2°C/W.....	5
• Updated <i>Overview, Application and Implementation, Device and Documentation Support</i> sections to extend detailed feature descriptions and more detailed information.	9
• Added parallel trace spacing recommendation to layout guidelines. Changed wording of "Avoid branches; buffer signals that must branch separately" to "Avoid branches; buffer each signal that must branch separately"	14



SN74LVC1G86

SCES222R – APRIL 1999 – REVISED AUGUST 2026

Changes from June 1, 2017 to August 12, 2026 (from Revision Q (June 2017) to Revision R (August 2026))

	Page
• Added <i>Thermal Information</i> table.....	5
• Changed Junction-to-ambient thermal resistance value for DBV package from: 206°C/W to: 357.1°C/W.....	5
• Changed Junction-to-ambient thermal resistance value for DCK package from: 252°C/W to: 371°C/W.....	5
• Changed tpd maximum value for $V_{CC} = 2.5V \pm 0.2V$ from: 4.5ns to: 4.9ns.....	6

The datasheet number will be changing.

Device Family	Change From:	Change To:
SN74LVC1G00	SCES212AB	SCES212AC
SN74LVC1G02	SCES213X	SCES213Y
SN74LVC1G240	SCES305L	SCES305M
SN74LVC1G80	SCES221S	SCES221T
SN74LVC1G32	SCES219V	SCES219W
SN74LVC1G126	SCES224R	SCES224S
SN74LVC1G08	SCES217Z	SCES217AA
SN74LVC1G132	SCES546D	SCES546E
SN74LVC1G38	SCES538G	SCES538H
SN74LVC1G79	SCES220U	SCES220V
SN74LVC1G125	SCES223T	SCES223U
SN74LVC1G86	SCES222Q	SCES222R

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/SN74LVC1G00>

<http://www.ti.com/product/SN74LVC1G02>

<http://www.ti.com/product/SN74LVC1G240>

<http://www.ti.com/product/SN74LVC1G80>

<http://www.ti.com/product/SN74LVC1G32>

<http://www.ti.com/product/SN74LVC1G126>

<http://www.ti.com/product/SN74LVC1G08>
<http://www.ti.com/product/SN74LVC1G132>
<http://www.ti.com/product/SN74LVC1G38>
<http://www.ti.com/product/SN74LVC1G79>
<http://www.ti.com/product/SN74LVC1G125>
<http://www.ti.com/product/SN74LVC1G86>

Reason for Change:	To accurately reflect device characteristics
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Anticipated impact on Form, Fit, Function, Quality or Reliability:	None
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Changes to product identification resulting from this PCN:	None
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Products Affected:

SN74LVC1G02DBVRG4	SN74LVC1G86DCKTG4.B	SN74LVC1G80DBVRE4
SN74LVC1G38DCKRG4	SN74LVC1G86DCKRG4.B	SN74LVC1G79DBVT.B
SN74LVC1G32DBVT	SN74LVC1G80DBVT	SN74LVC1G32DCKRE4
SN74LVC1G08DBVTG4.B	SN74LVC1G125DCKTG4.B	SN74LVC1G126DBVRG4.A
SN74LVC1G08DCKRG4	74LVC1G240DCKTG4	SN74LVC1G08DBVTG4
SN74LVC1G08DCKTE4	74LVC1G240DBVTG4.B	SN74LVC1G00DCKT
SN74LVC1G79DCKT	SN74LVC1G00DBVRG4	SN74LVC1G00DCKRG4.B
SN74LVC1G32DCKT.B	SN74LVC1G132DBVTG4.B	SN74LVC1G08DCKRE4
74LVC1G125DCKRG4.B	SN74LVC1G79DBVTG4.B	74LVC1G125DCKTE4
74LVC1G240DBVTG4	SN74LVC1G80DBVT.B	SN74LVC1G126DCKT
SN74LVC1G132DCKRG4.A	SN74LVC1G86DBVRG4	SN74LVC1G79DCKRG4
SN74LVC1G02DCKTG4.B	SN74LVC1G126DCKT.B	74LVC1G132DCKTG4.B
74LVC1G240DCKRG4	74LVC1G125DCKRG4	74LVC1G126DCKTG4.B
SN74LVC1G00DCKRG4	SN74LVC1G132DCKT.B	SN74LVC1G125DBVT.B
74LVC1G126DCKTG4	74LVC1G125DCKTG4.B	SN74LVC1G38DBVTG4.B
SN74LVC1G02DBVRE4	74LVC1G240DCKTG4.B	74LVC1G240DCKRE4
SN74LVC1G132DCKT	74LVC1G125DBVTG4	SN74LVC1G02DBVRG4.B
SN74LVC1G00DBVRE4	SN74LVC1G32DCKR-NG	SN74LVC1G08DCKT
74LVC1G132DCKRG4	SN74LVC1G86DCKT	74LVC1G126DCKRE4
SN74LVC1G00DCKRG4.A	74LVC1G125DBVRE4.B	SN74LVC1G00DCKTG4
74LVC1G125DCKTG4	SN74LVC1G32DBVRG4	74LVC1G240DBVRG4
SN74LVC1G38DBVRG4	SN74LVC1G80DBVRG4	SN74LVC1G126DBVT
SN74LVC1G38DCKT	SN74LVC1G32DCKT	SN74LVC1G240DCKT.B
SN74LVC1G38DBVT.B	SN74LVC1G02DCKT	SN74LVC1G32DBVRG4.B
74LVC1G240DCKRG4.B	74LVC1G126DCKRG4.A	SN74LVC1G08DCKRG4.B
SN74LVC1G00DBVT.B	SN74LVC1G79DBVT	74LVC1G132DCKTG4
SN74LVC1G08DBVT	SN74LVC1G00DBVTG4.B	SN74LVC1G32DCKTG4.B
SN74LVC1G38DCKRG4.A	SN74LVC1G02DBVTG4	74LVC1G132DCKRG4.B
SN74LVC1G80DCKRG4	SN74LVC1G08DCKTG4	74LVC1G126DCKRG4
74LVC1G240DBVRG4.B	SN74LVC1G86DBVRE4	SN74LVC1G126DBVRG4.B
SN74LVC1G38DCKT.B	SN74LVC1G38DBVT	SN74LVC1G32DBVTG4
SN74LVC1G240DCKT	SN74LVC1G125DBVT	SN74LVC1G125DCKT

SN74LVC1G240DBVT.B	SN74LVC1G08DBVT.B	74LVC1G125DCKRE4
SN74LVC1G240DBVT	74LVC1G125DBVRG4	SN74LVC1G08DBVTE4
SN74LVC1G86DCKT.B	SN74LVC1G126DBVT.B	SN74LVC1G132DBVTG4
SN74LVC1G132DBVT.B	SN74LVC1G79DCKTG4	SN74LVC1G32DCKR-NG.B
SN74LVC1G126DCKTG4.B	SN74LVC1G126DCKTG4	SN74LVC1G08DCKTG4.B
SN74LVC1G02DBVT.B	SN74LVC1G02DBVT	74LVC1G132DBVRG4
SN74LVC1G126DBVRG4	SN74LVC1G86DBVRG4.B	SN74LVC1G38DBVRG4.B
SN74LVC1G79DBVTG4	SN74LVC1G38DBVRE4	SN74LVC1G32DBVRE4
74LVC1G132DBVRG4.B	SN74LVC1G132DCKRG4	SN74LVC1G86DCKRE4
74LVC1G125DBVRE4	SN74LVC1G86DBVT	SN74LVC1G00DBVTE4
SN74LVC1G00DBVTG4	SN74LVC1G32DCKRG4.B	SN74LVC1G08DCKR-NG.B
SN74LVC1G240DCKTG4.B	SN74LVC1G132DBVT	SN74LVC1G86DBVT.B
SN74LVC1G38DBVTG4	SN74LVC1G80DBVRG4.B	SN74LVC1G00DCKRE4
SN74LVC1G32DCKRG4	SN74LVC1G79DCKRG4.B	SN74LVC1G00DCKT.B
SN74LVC1G00DBVRG4.B	SN74LVC1G80DCKT.B	SN74LVC1G02DCKRG4.B
SN74LVC1G240DCKTG4	SN74LVC1G79DCKT.B	SN74LVC1G02DCKRG4
SN74LVC1G02DBVTG4.B	SN74LVC1G02DCKT.B	SN74LVC1G125DCKTG4
SN74LVC1G86DCKRG4	SN74LVC1G80DCKRG4.B	74LVC1G125DBVTE4
SN74LVC1G00DBVT	SN74LVC1G38DCKRG4.B	SN74LVC1G32DCKRG4.A
74LVC1G125DBVRG4.B	74LVC1G125DBVTG4.B	SN74LVC1G80DBVTG4.B
SN74LVC1G79DCKTG4.B	SN74LVC1G00DCKTG4.B	SN74LVC1G08DCKT.B
SN74LVC1G32DCKTG4	SN74LVC1G32DBVTG4.B	74LVC1G125DBVTE4.B
SN74LVC1G125DCKT.B	74LVC1G126DBVTG4	74LVC1G126DBVTE4
SN74LVC1G02DCKTG4	SN74LVC1G132DCKRG4.B	74LVC1G126DBVTG4.B
SN74LVC1G08DCKR-NG	SN74LVC1G86DCKTG4	SN74LVC1G80DCKT
SN74LVC1G32DBVT.B	SN74LVC1G80DBVTG4	SN74LVC1G02DCKRE4
74LVC1G126DCKRG4.B		

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